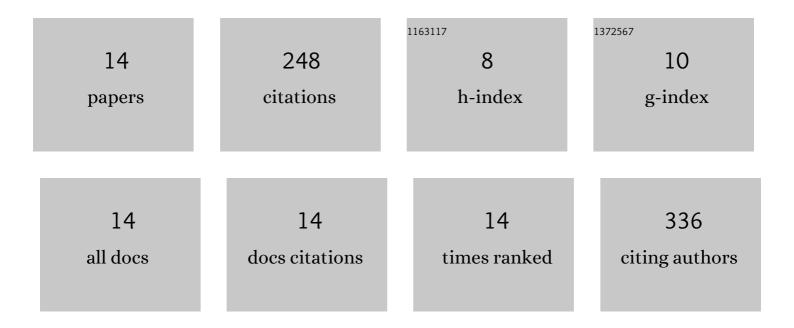
## Di Jiang

## List of Publications by Year in descending order

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| #  | Article   | IF   | CITATIONS |
|----|---|------|-----------|
| 1  | A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds.<br>Flexible and Printed Electronics, 2017, 2, 025003.                                  | 2.7  | 6         |
| 2  | Embedded Fin‣ike Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016,<br>12, 1521-1526.  | 10.0 | 15        |
| 3  | Flexible Multifunctionalized Carbon Nanotubesâ€Based Hybrid Nanowires. Advanced Functional<br>Materials, 2015, 25, 4135-4143.   | 14.9 | 20        |
| 4  | Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of<br>Electronic Materials, 2015, 44, 2898-2907.  | 2.2  | 21        |
| 5  | Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE<br>Electron Device Letters, 2015, 36, 499-501.   | 3.9  | 44        |
| 6  | Reliability of carbon nanotube bumps for chip on glass application. , 2014, , .   |      | 2         |
| 7  | Carbon nanotube/solder hybrid structure for interconnect applications. , 2014, , .  |      | 0         |
| 8  | Chemically vapor deposited carbon nanotubes for vertical electronics interconnect in packaging applications. , 2014, , .  |      | 2         |
| 9  | Carbon nanotubes for electronics manufacturing and packaging: from growth to integration.<br>Advances in Manufacturing, 2013, 1, 13-27.   | 6.1  | 22        |
| 10 | Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in<br>Manufacturing, 2013, 1, 236-240.  | 6.1  | 2         |
| 11 | Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180. | 2.4  | 30        |
| 12 | Reliability of carbon nanotube bumps for chip on film application. , 2013, , .  |      | 0         |
| 13 | Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron<br>Device Letters, 2012, 33, 420-422.   | 3.9  | 67        |
| 14 | Formation of three-dimensional carbon nanotube structures by controllable vapor densification.<br>Materials Letters, 2012, 78, 184-187.   | 2.6  | 17        |